

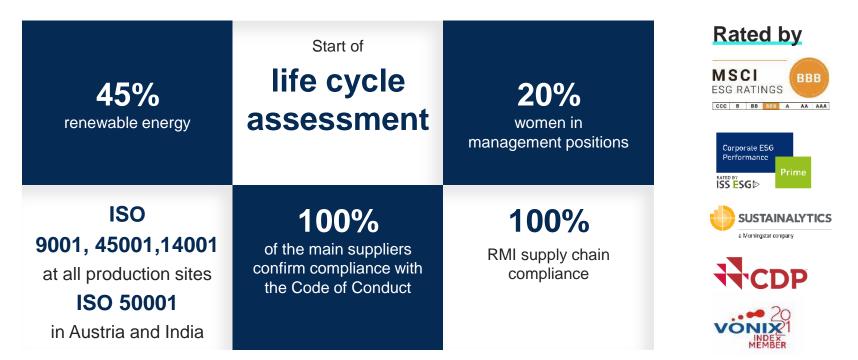
# CONSISTENCY IN CHANGE

#### **Erste Group - Innovation Conference 2021**

Investor and Analyst Presentation



#### Highlights FY 20/21





# **LEADING PROVIDER OF HIGH-END PCBs & IC SUBSTRATES**

#### Well positioned for the future

#### Unique market position

- Broad product portfolio to serve all growth markets
- Long-standing customer relationships with technology and market leaders
- Technology innovator due to continuous R&D efforts
- Quality benchmark with outstanding process know-how, productivity and efficiency

#### Growth oriented strategy

- Megatrend-driven markets with attractive growth potential
- Address growth opportunities with incremental investments
- Constant outperformance of the PCB & substrates market

€1.2 bn **>€2 bn** revenue

revenue FY 23/24

# 5 ABF substrates producer

worldwide

FY 20/21

#3 in FY 24/25

#2 high-end PCB producer worldwide

# **ONE**

of the leading high-end PCB producers worldwide

# **GLOBAL FOOTPRINT**



 AT&S Headquarters

<sup>1</sup> Staff, Average, FTE, FY 20/21; 80 employees in other locations

 $\bigcirc$ 



# **MARKET SEGMENTS & PRODUCT APPLICATIONS**



#### Segment Mobile Devices & Substrates

#### Segment Automotive, Industrial, Medical

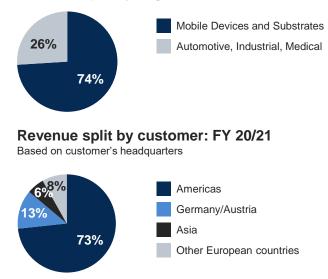




#### In € mn +10% CAGR 1188 1028 1001 992 815 23% 24% 21% 19% 16% 250 246 226 195 131\* 2016/17 2017/18 2018/19 2019/20 2020/21

EBITDA margin

#### Revenue split by segment: FY 20/21

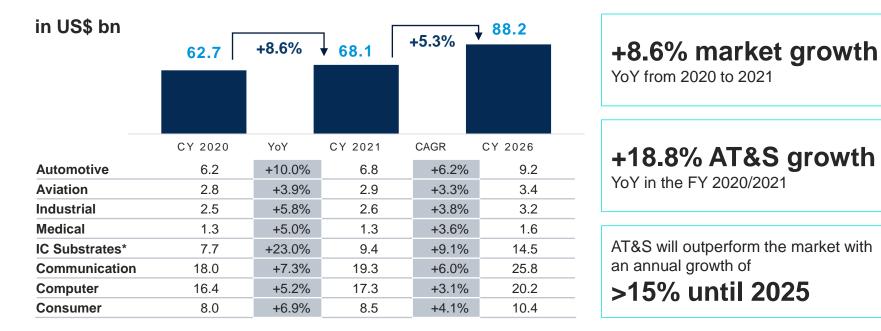


\* Based on ramp-up effects for new plants in China

EBITDA

Revenue

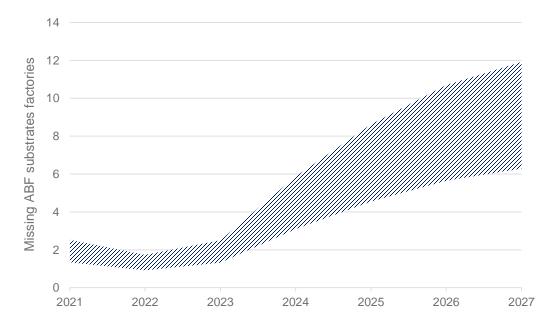
# AT&S OUTPERFORMS PCB & IC SUBSTRATES\* MARKET GROWTH





# **CONTINUOUS GROWTH IN ABF SUBSTRATES DEMAND**

Actual gap of required ABF substrates factories to satisfy demand



- Actual gap depends on actual mix in product and technology demand
- Increasing complexity of high-end products leads to ongoing strong ABF substrates demand
- Complexity requires increasing layer count and larger products
- Current supply shortage is predominantly in high-end products
- Especially server and Al applications drive the demand

## STRATEGIC BUSINESS DRIVERS





# GAME CHANGERS ARE DRIVING OUR BUSINESS

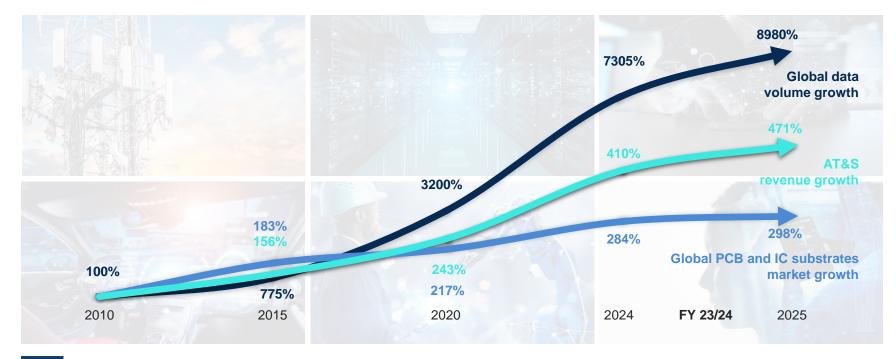
New technologies and systems bring a significant data volume increase





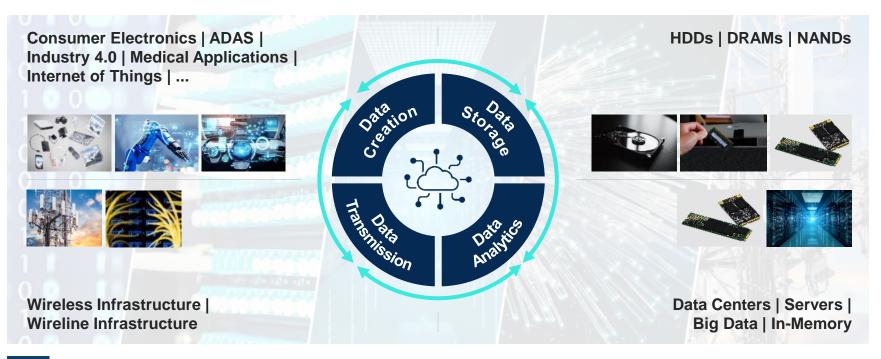


# GLOBAL DATA VOLUME DEVELOPMENT DRIVES AT&S GROWTH





# **DIGITALISATION REQUIRES DATA MANAGEMENT**



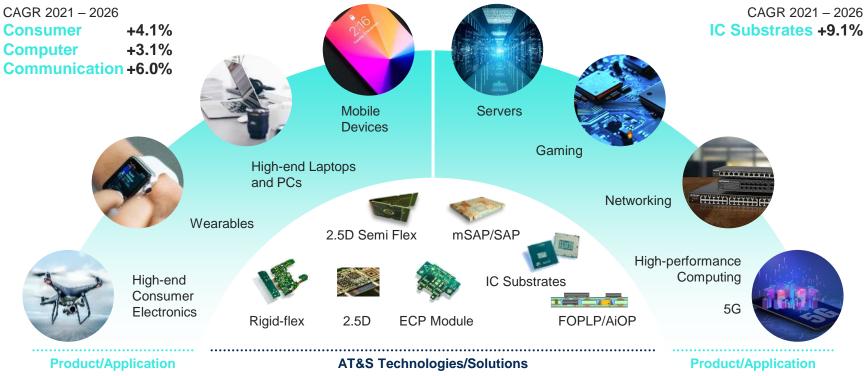


## AT&S GROWTH ENABLED BY APPLICATIONS AND INNOVATION & SUSTAINABILITY

Investor and Analyst Presentation



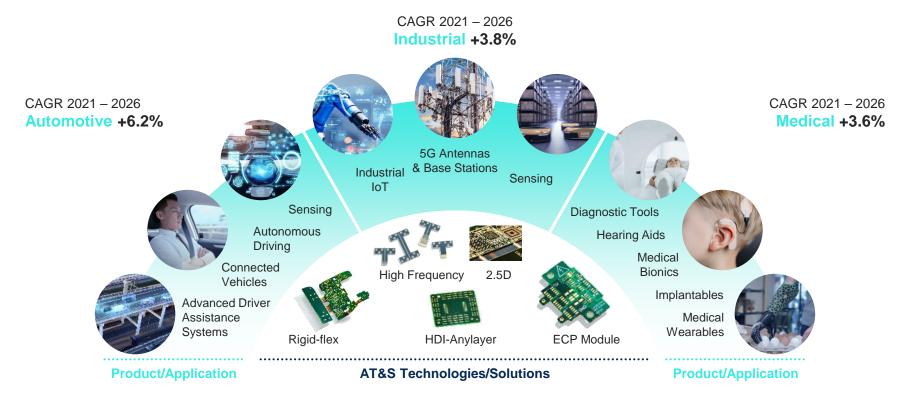
# **MOBILE DEVICES AND SUBSTRATES**



\* PCB/IC Substrates Market Growth: CAGR 2021-2026



# **AUTOMOTIVE – INDUSTRIAL – MEDICAL**





# **R&D – BASIS FOR TECHNOLOGY LEADERSHIP**



Status: FY 2020/21

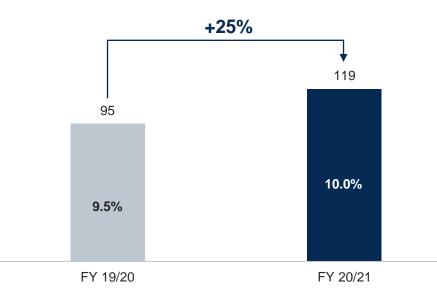
\*Share of revenue of technologically innovative products made in the last three years (previously: Innovation Revenue Rate)



# **R&D INVESTMENTS**

#### A key revenue and margin driver

in € mn

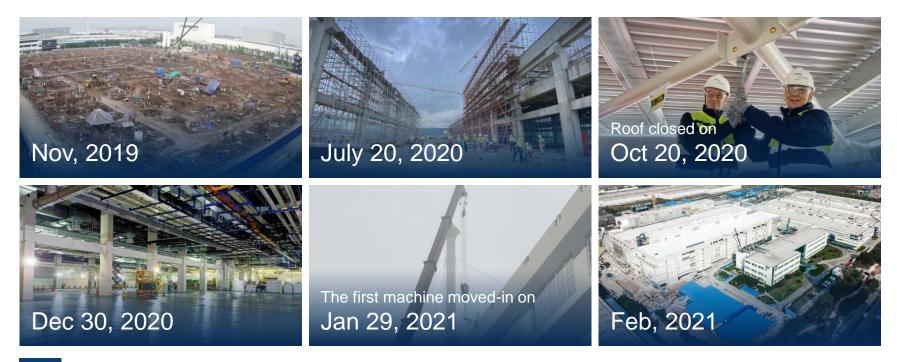


# € 246 mn revenue with new products

Miniaturisation and functional integration	Fast signal transmission
Performance and performance efficiency	Manufacturing of the future

# **CAPACITY EXPANSION AT CHONGQING III**

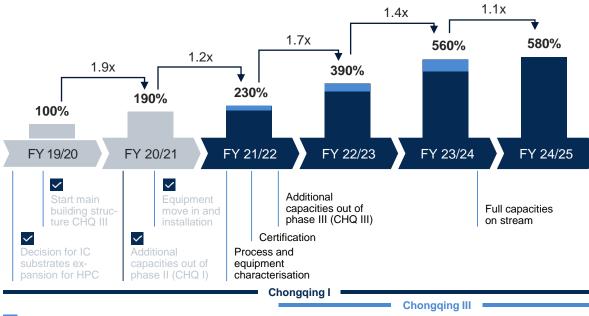
On the way to becoming one of the leading high-end ABF substrates producers





# **RAMP OF CHONGQING III EARLIER THAN EXPECTED**

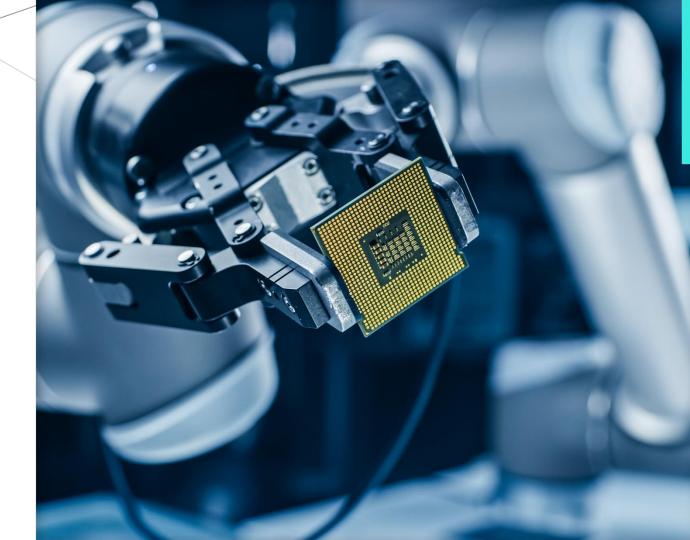
#### ABF substrates output capacity



Additional output capacity due to investment increase and earlier production start in CHQ III

- CHQ III: Production will already be starting in FY 21/22
- Additional € 200 mn investment in CHQ III
- Full capacities available with the beginning of CY 2024 (Q4 23/24)

## **RESULTS FY 20/21**



# **KEY DEVELOPMENTS FY 20/21**

#### Strong full-year results demonstrate AT&S resilience and agility

Growing profitably with served markets

- Additional capacities and strong demand drive ABF substrates business
- Mobile applications supported by customer and application diversification
- PCBs for modules contribute to overall revenue growth
- Automotive with ongoing recovery and Q4 above last year
- Medical & Healthcare with stable performance due to improved demand
- Industrial segment with positive development thanks to better product mix
- Capacity expansion in Chongqing faster than expected



# FY 20/21 RESULTS SUMMARY

#### Revenue at historic high

Revenue +19%

€1,188 mn

- Five year CAGR 8%
- Negative FX effects of € 37 mn

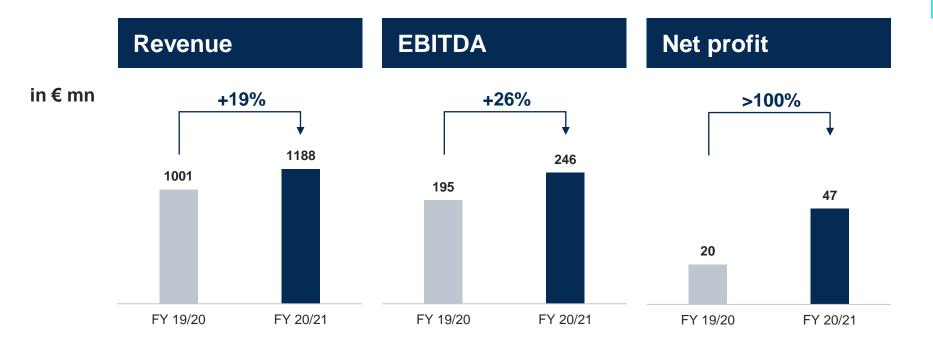
EBITDA margin **+130 bps** 

 Strong EBITDA margin despite headwinds from COVID-19 impacts ROCE +300 bps

 Driven by strong operating result

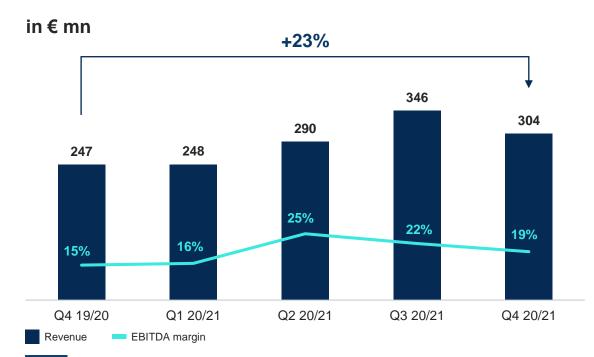


# FY 20/21 RESULTS SUMMARY





# **QUARTERLY DEVELOPMENT**



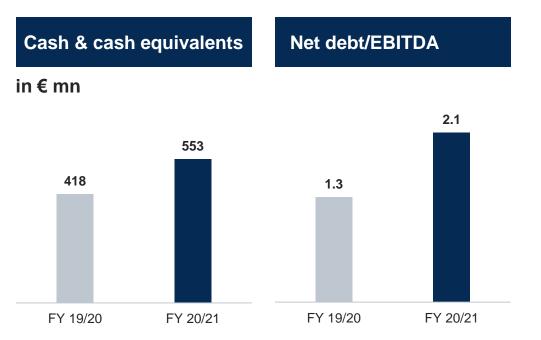
Highest Q4 revenue in history

Part of **seasonality mitigated** by growing IC substrates business

**Profitability** clearly improved

# **FY 20/21 FINANCIAL POSITION**

Solid financial structure for future growth



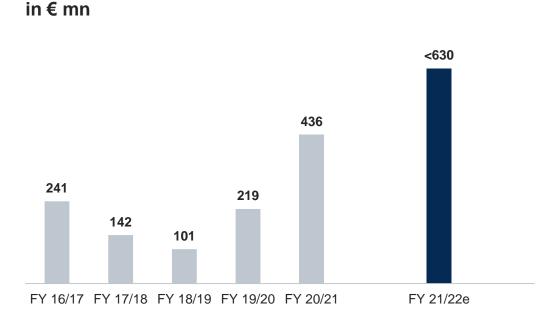
## **Balancing capital allocation**

- Deploying capital with clear approach to invest in strategic growth markets
- Increasing net debt level by € 262 m in FY 20/21 due to investments in additional IC substrates capacities

Sound investment decisions to generate strong operating and free cash flow in the future.

# **NET CAPEX**

#### Investments in IC substrates and module PCBs consistently continued



## Capex outlook 2021/22

- Depending on market developments CAPEX for maintenance and tech upgrade of up to € 100 m
- CAPEX for strategic projects of up to € 450 m plus € 80 m due to timing variances

# **BALANCE SHEET**

€mn	31.03.2020	31.03.2021	Change in %	
Total assets	1,854	2,390	+29%	Ongoing expansion and technology upgrades main driver for increase in total assets
Equity	760	802	+6%	
Equity ratio	41%	34%	-740bps	Increase in total assets weighs on equity ratio
Net debt	247	509	>100%	Higher CAPEX feeds into liquidity and drives up net debt

# GUIDANCE FY 21/22

Further growth ahead

FY 21/22		
Growth	Revenue growth of 13 – 15%	
Profitability	Adjusted EBITDA margin of 21 – 23% Adjustment: start-up effects of the Chongqing project with an amount of appr. € 40 mn	
CAPEX	<ul> <li>Maintenance and tech-upgrades € 100 mn</li> <li>CAPEX from PY (timing variances) € 80 mn</li> <li>Expansion projects € 450 m</li> </ul>	
Dividend proposal	€ 0.39 per share (for FY 20/21)	



# **MEDIUM-TERM GUIDANCE**

Technology development to module integration and capacity expansion

First choice for advanced applications

#### Expansion of technology leadership

- Leading provider of new interconnect solutions
- Innovation revenue rate: > 20%

#### Focus on continued profitable growth

- 2023/24: Revenue target of more than € 2 bn
- 2023/24: EBITDA margin target of 25 30%

#### Creation of shareholder value and robust financial structure

- Medium-term ROCE above 12%
- Net debt / EBITDA: < 3/Equity ratio: > 40%/Average Finance costs: < 2%</p>

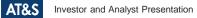
#### Sustainability management

- 80% renewable energy
- Eco-balancing of product groups
- 30% women in management positions









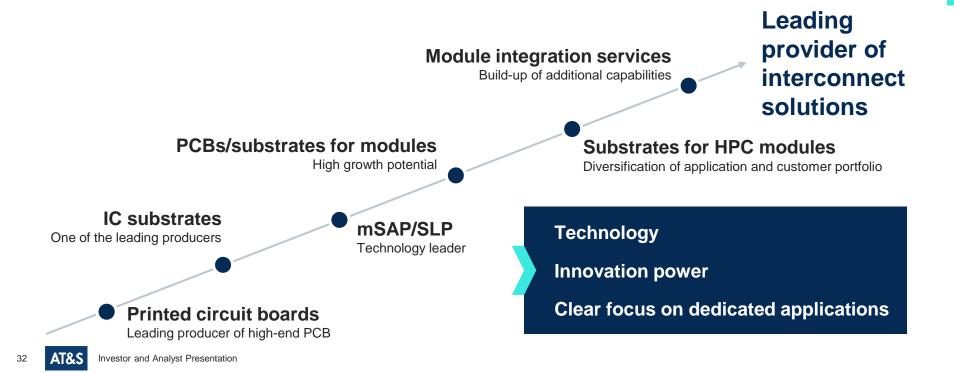
# **MARKET PLAYERS IN THE HIGH-END SEGMENT**

HDI Technology (2019)		ABF Substrates (2019)	
1	Compeq	1	Ibiden
2	AT&S	2	Unimicron
3	TTM	3	SEMCO
4	Unimicron	4	Shinko
5	Tripod	5	AT&S
6	Meiko	6	Kyocera
7	Zhen Ding	7	Nan Ya PCB
8	Korea Circuit	8	Kinsus

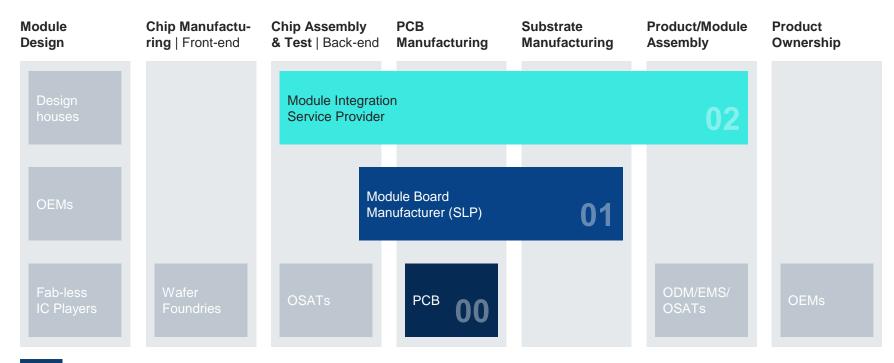
Source: Prismark, JMS, AT&S assessment

# **MORE THAN AT&S**

Broadening the service range and opening up of new business opportunities

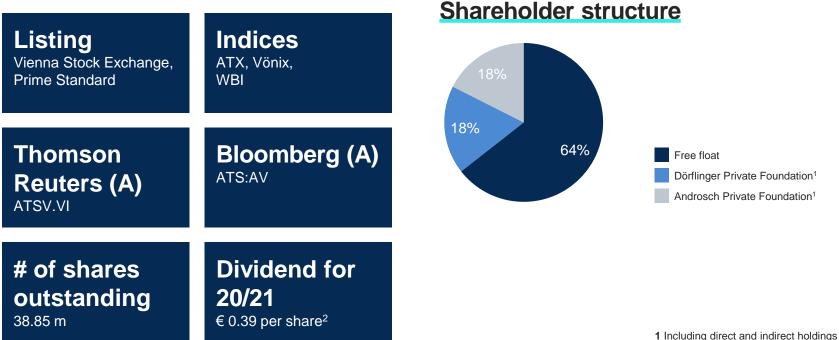


# **AT&S SOLUTIONS FOR THE ELECTRONICS INDUSTRY**





# AT&S – STOCK PROFILE





# **THANK YOU FOR YOUR ATTENTION**

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